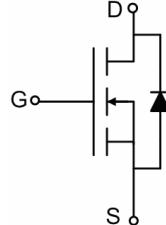
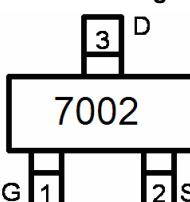


## FNK N-Channel Enhancement Mode Power MOSFET

<p><b>General Features</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS} = 60V, I_D = 0.115A</math></li> <li>● <math>R_{DS(ON)} &lt; 3\Omega @ V_{GS}=5V</math></li> <li>● <math>R_{DS(ON)} &lt; 2\Omega @ V_{GS}=10V</math></li> <li>● Lead free product is acquired</li> <li>● Surface mount package</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● Direct logic-level interface: TTL/CMOS</li> <li>● Drivers: relays, solenoids, lamps, hammers, display, memories, transistors, etc.</li> <li>● Battery operated systems</li> <li>● Solid-state relays</li> </ul>	 <p><b>Schematic diagram</b></p>  <p><b>Marking and pin assignment</b></p>  <p><b>SOT-23 top view</b></p>
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### Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
7002	2N7002	SOT-23	Ø180mm	8 mm	3000 units

### Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous@ Current-Pulsed (Note 1)	$I_D$	0.115	A
	$I_{DM}$	0.8	A
Maximum Power Dissipation	$P_D$	0.2	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	625	°C/W
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### Electrical Characteristics (TC=25°C unless otherwise noted)

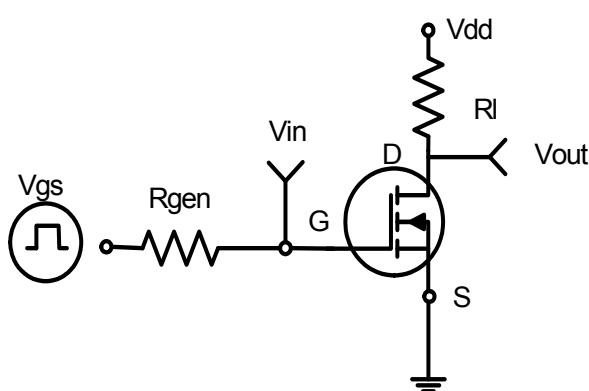
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	60	68	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$	-	-	1	$\mu A$

Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	1	1.7	2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =5V, I <sub>D</sub> =0.05A	-	1.3	3	Ω
		V <sub>GS</sub> =10V, I <sub>D</sub> =0.5A	-	1.1	2	Ω
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =0.2A	0.08	-	-	S
<b>Dynamic Characteristics (Note4)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, F=1.0MHz	-	20	50	PF
Output Capacitance	C <sub>oss</sub>		-	10	20	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	3.6	5	PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, I <sub>D</sub> =0.2A V <sub>GS</sub> =10V, R <sub>GEN</sub> =10Ω	-	10	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	50	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	17	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	10	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =0.115A, V <sub>GS</sub> =4.5V	-	1.7	3	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =0.115A	-	-	1.2	V
Diode Forward Current (Note 2)	I <sub>s</sub>		-	-	0.115	A

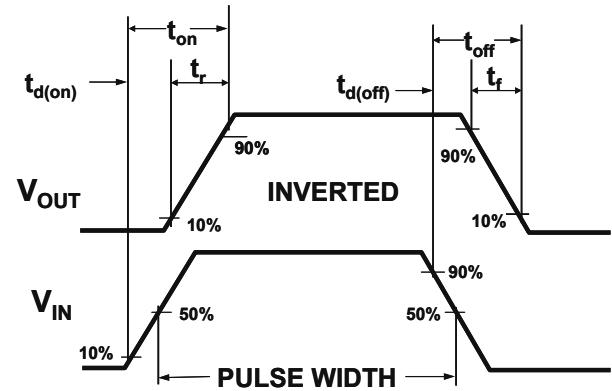
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

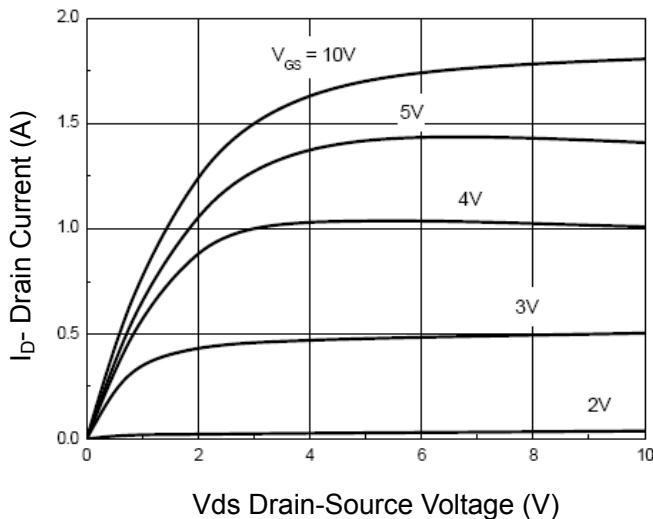
### Typical Electrical And Thermal Characteristics



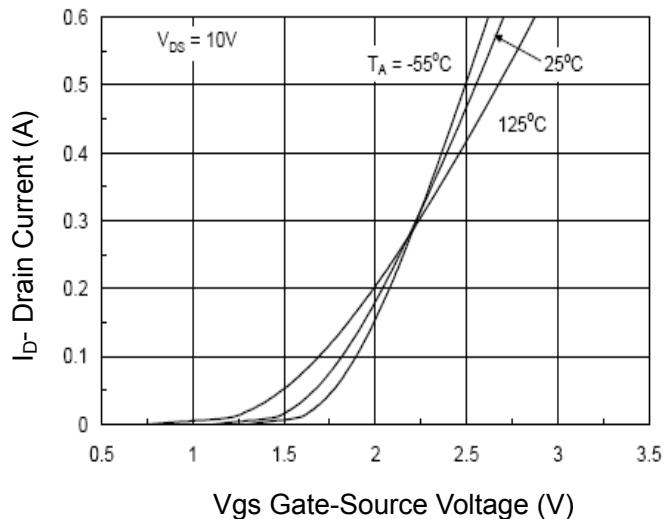
**Figure 1:Switching Test Circuit**



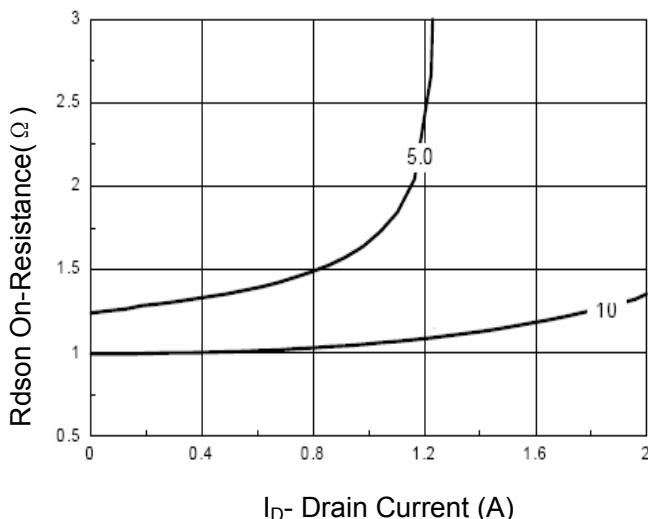
**Figure 2:Switching Waveforms**



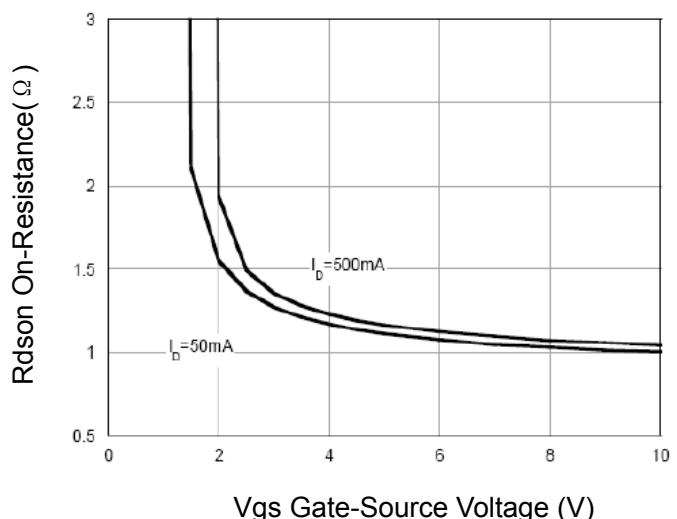
**Figure 3 Output Characteristics**



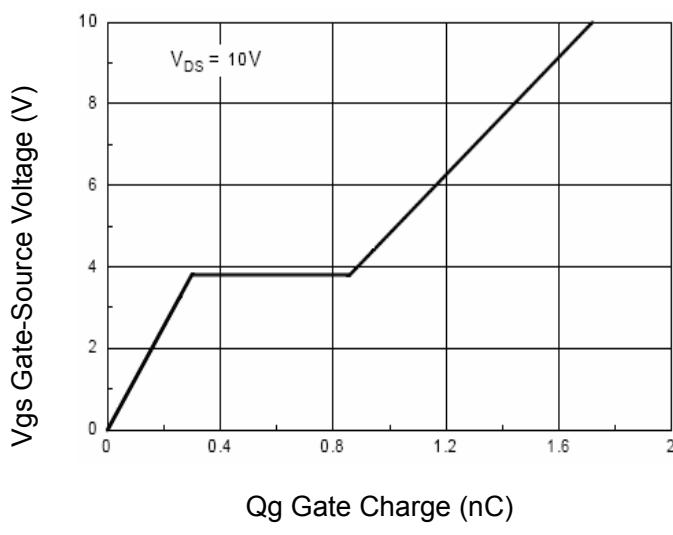
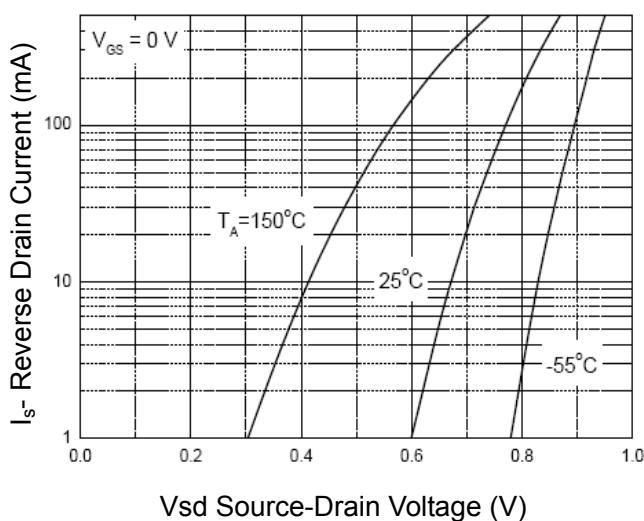
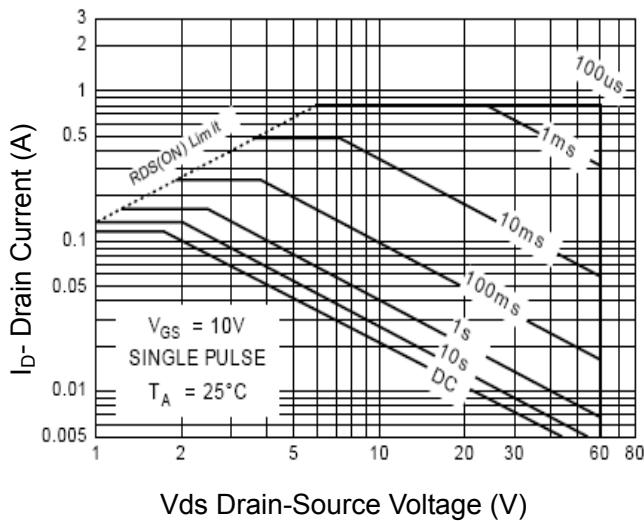
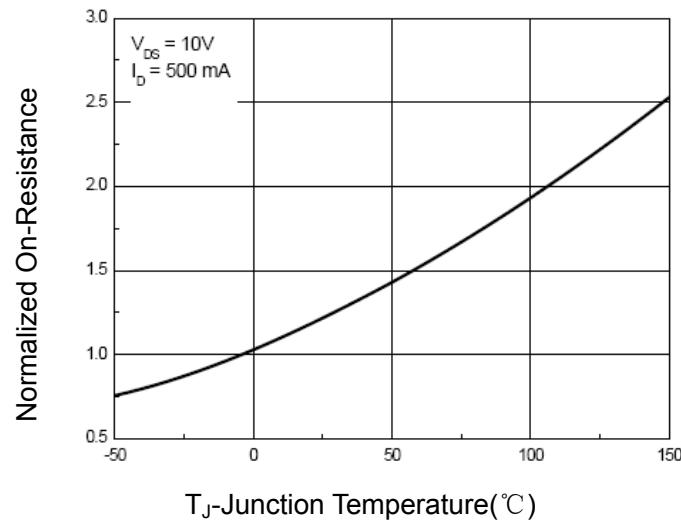
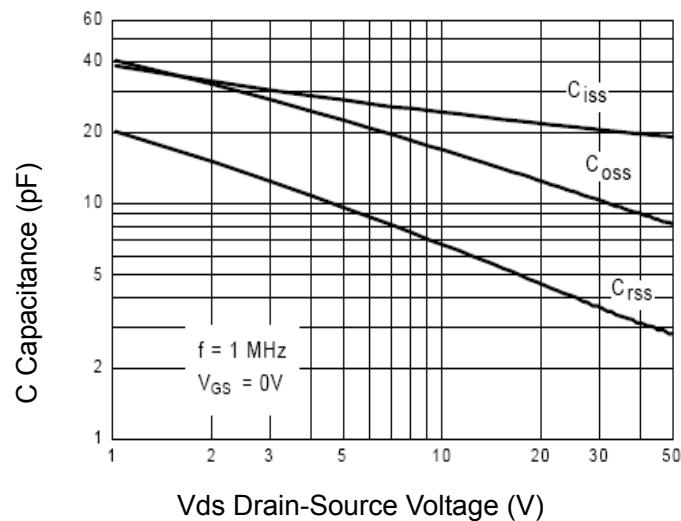
**Figure 4 Transfer Characteristics**

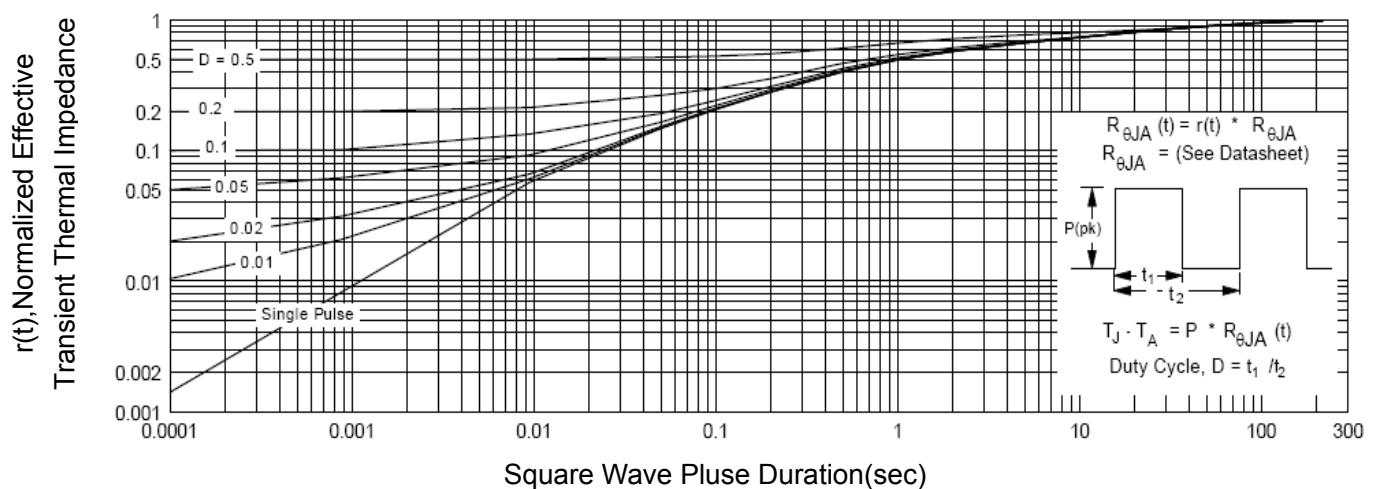


**Figure 5 Drain-Source On-Resistance**

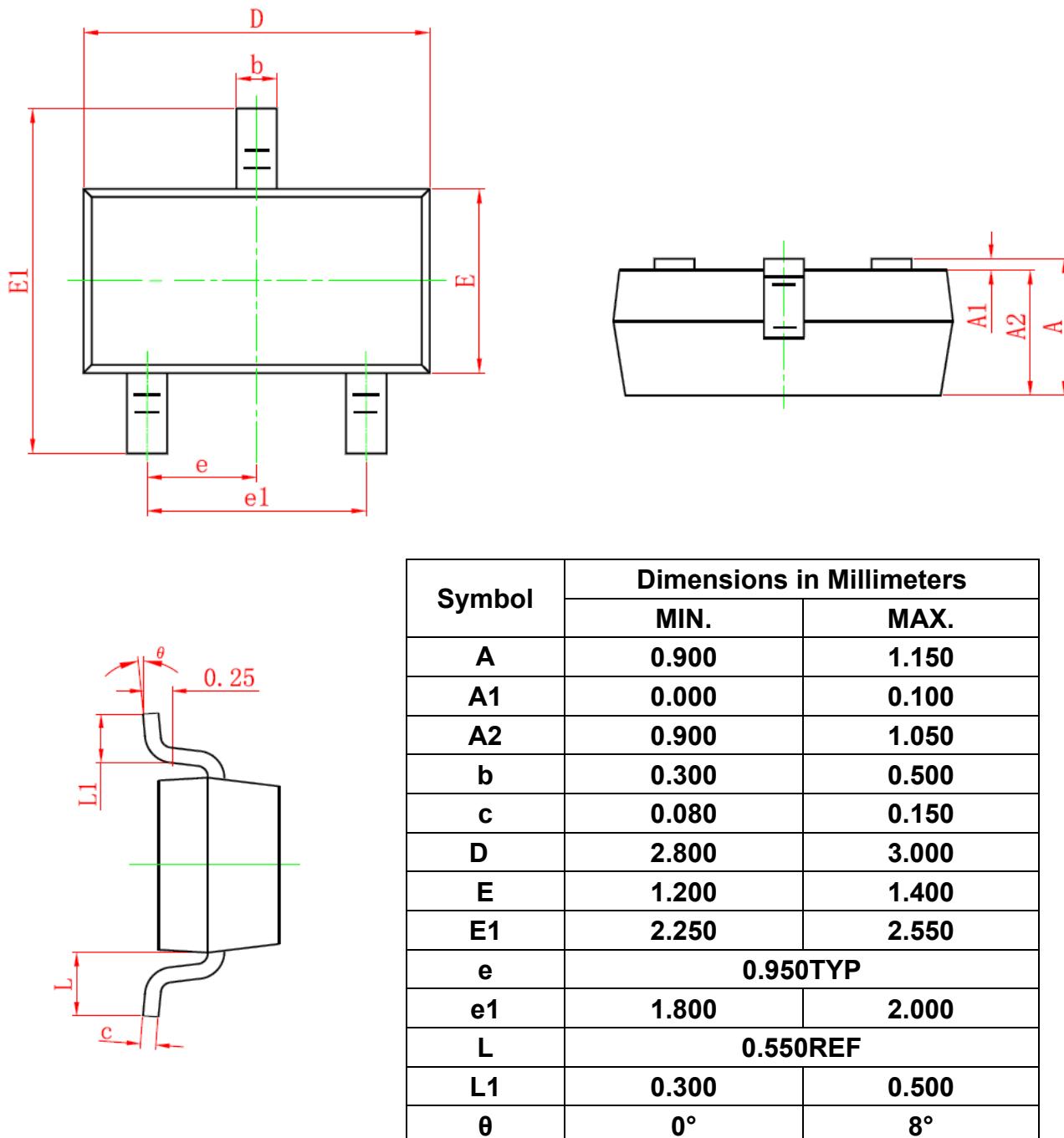


**Figure 6 Rdson vs Vgs**


**Figure 7 Gate Charge**

**Figure 8 Source-Drain Diode Forward**

**Figure 10 Safe Operation Area**

**Figure 9 Drain-Source On-Resistance**

**Figure 11 Capacitance vs Vds**



**Figure 12 Normalized Maximum Transient Thermal Impedance**

**SOT-23 Package Information**

**Notes**

1. All dimensions are in millimeters.
2. Tolerance  $\pm 0.10\text{mm}$  (4 mil) unless otherwise specified
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.